

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/06/2022

Details for "OPA2344EA/2K5"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA2344EA/2K5	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DGK 8	3x3x1	29

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.029054	99.989675	999897	0.10033	1003
Not Categorized	Proprietary Materials		0.000003	0.010325	103	0.00001	0
Sub-Total			0.029057	100	1000000	0.10034	1003
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.193001	82.000025	820000	0.666476	6665
Thermoplastics	Epoxy	85954-11-6	0.042366	17.999975	180000	0.146299	1463
Sub-Total			0.235367	100	1000000	0.812775	8128
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	13.036772	99.7	997000	45.018901	450189
Magnesium and Its Alloys	Magnesium	7439-95-4	0.006538	0.05	500	0.022577	226
Other Inorganic Materials	Silicon	7440-21-3	0.03269	0.25	2500	0.112886	1129
Sub-Total			13.076	100	1000000	45.154364	451544
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.3892	97.3	973000	1.343995	13440
Precious Metals	Gold	7440-57-5	0.0012	0.3	3000	0.004144	41
Precious Metals	Palladium	7440-05-3	0.0084	2.1	21000	0.029007	290
Precious Metals	Silver	7440-22-4	0.0012	0.3	3000	0.004144	41
Sub-Total			0.4	100	1000000	1.38129	13813
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	13.471179	92.499998	925000	46.519006	465190
Other Plastics and Rubber	Carbon Black	1333-86-4	0.072817	0.499999	5000	0.251453	2515
Thermoplastics	Epoxy	85954-11-6	1.019441	7.000003	70000	3.520359	35204
Sub-Total			14.563437	100	1000000	50.290818	502908
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.65458	100	1000000	2.260412	22604
Sub-Total			0.65458	100	1000000	2.260412	22604
Total			28.958441			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 05/06/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.